



Board Stack Report

Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste			
2		Top Overlay			
3		Top Solder	Solder Resist	0.010mm	3.5
4		Top Layer	Copper	0.036mm	
5		Dielectric 1	FR-4	1.508mm	4.8
6		Bottom Layer	Copper	0.036mm	
7		Bottom Solder	Solder Resist	0.010mm	3.5
8		Bottom Overlay			
9		Bottom Paste			
		Height : 1.600mm			




Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
▽	2	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c250h100
✖	2	1.321mm (52.00mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
○	14401	0.152mm (6.00mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v25h15
14405 Total								

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.39mil	3.5	
3	Top Layer	Copper	1.42mil		
4	Dielectric 1	FR-4	59.37mil	4.8	
5	Bottom Layer	Copper	1.42mil		
6	Bottom Solder	Solder Resist	0.39mil	3.5	
7	Bottom Overlay				



Layer	Name	Material	Thickness	Constant	Board Layer Stack
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2	Top Solder	Solder Resist	0.39mil	3.5	
3	Top Layer	Copper	1.42mil		
4	Dielectric 1	FR-4	59.37mil	4.8	
5	Bottom Layer	Copper	1.42mil		
6	Bottom Solder	Solder Resist	0.39mil	3.5	
7	Bottom Overlay				



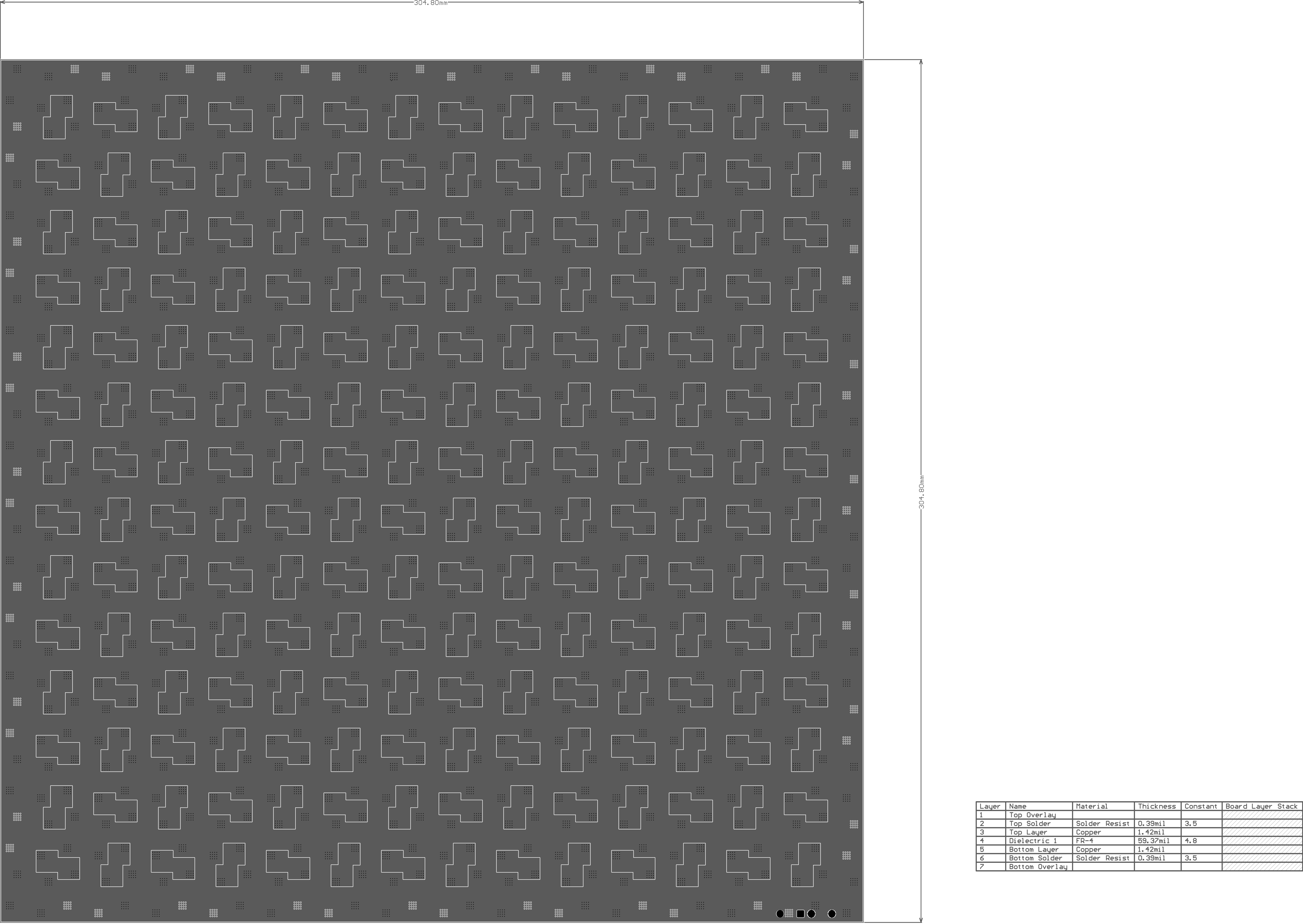
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.39mil	3.5	
3	Top Layer	Copper	1.42mil		
4	Dielectric 1	FR-4	59.37mil	4.8	
5	Bottom Layer	Copper	1.42mil		
6	Bottom Solder	Solder Resist	0.39mil	3.5	
7	Bottom Overlay				

304.80mm


Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.39mil	3.5	
3	Top Layer	Copper	1.42mil		
4	Dielectric 1	FR-4	59.37mil	4.8	
5	Bottom Layer	Copper	1.42mil		
6	Bottom Solder	Solder Resist	0.39mil	3.5	
7	Bottom Overlay				

304.80mm

Layer	Name	Material	Thickness	Constant	Board Layer Stack
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304.80mm


Layer	Name	Material	Thickness	Constant	Board Layer Stack
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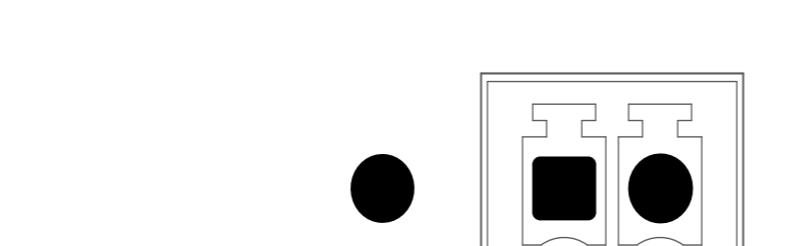




Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
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304.80mm


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5	Bottom Layer	Copper	1.42mil		
6	Bottom Solder	Solder Resist	0.39mil	3.5	
7	Bottom Overlay				



304.80mm


Layer	Name	Material	Thickness	Constant	Board Layer Stack
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